

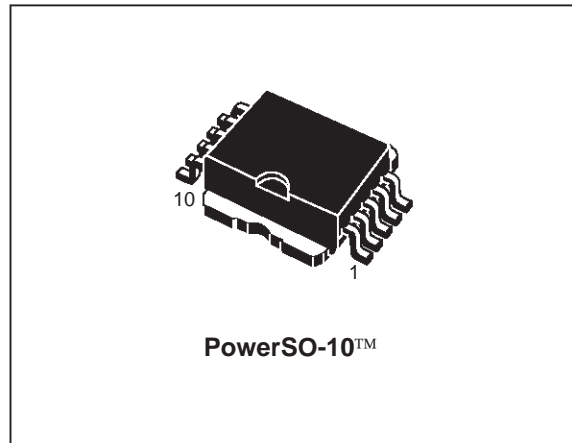


VND670SP

DUAL HIGH SIDE SWITCH WITH DUAL POWER MOS GATE DRIVER (BRIDGE CONFIGURATION)

TYPE	R _{DS(on)}	I _{OUT}	V _{DSS}
VND670SP	30 mΩ	15 A	40 V

- OUTPUT CURRENT: 15A PER CHANNEL
- 5V LOGIC LEVEL COMPATIBLE INPUTS
- GATE DRIVE FOR TWO EXTERNAL POWER MOS
- UNDERVOLTAGE AND OVERVOLTAGE SHUT-DOWN
- OVERVOLTAGE CLAMP
- THERMAL SHUT DOWN
- CROSS-CONDUCTION PROTECTION
- CURRENT LIMITATION
- VERY LOW STAND-BY POWER CONSUMPTION
- PWM OPERATION UP TO 10 KHz
- PROTECTION AGAINST:
 - LOSS OF GROUND AND LOSS OF V_{CC}
- REVERSE BATTERY PROTECTION (*)

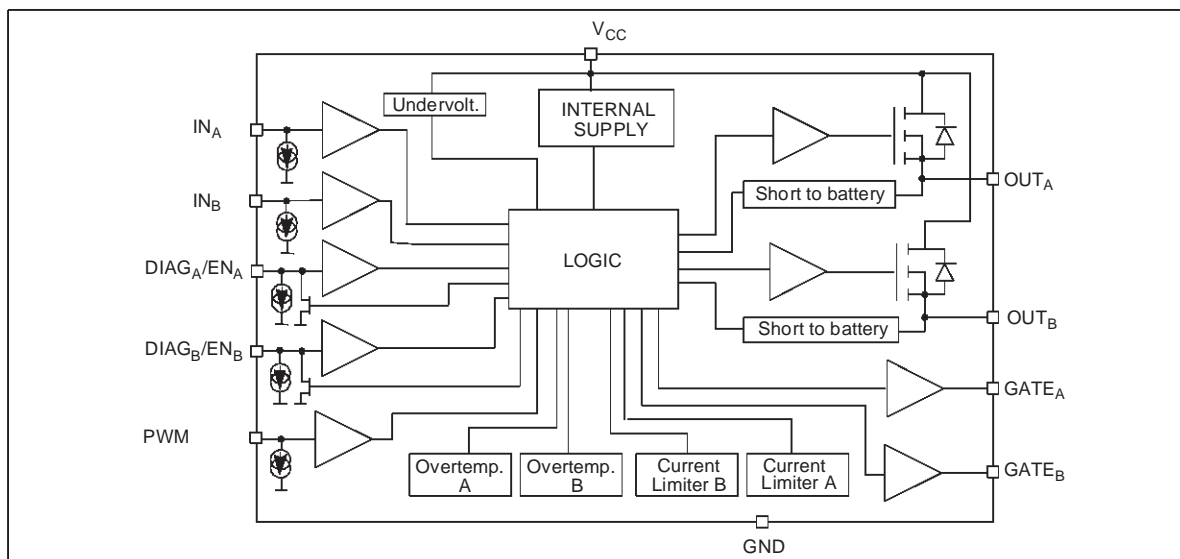


configuration. The device integrates two 30 mΩ Power MOSFET in high side configuration, and provides gate drive for two external Power MOSFET used as low side switches. IN_A and IN_B allow to select clockwise or counter clockwise drive or brake; DIAG_A/EN_A, DIAG_B/EN_B allow to disable one half bridge and feedback diagnostic. Built-in thermal shut-down, combined with a current limiter, protects the chip in overtemperature and short circuit conditions. Short to battery protects the external connected low-side Power MOSFET.

DESCRIPTION

The VND670SP is a monolithic device made using STMicroelectronics VIPower technology, intended for driving motors in full bridge

BLOCK DIAGRAM

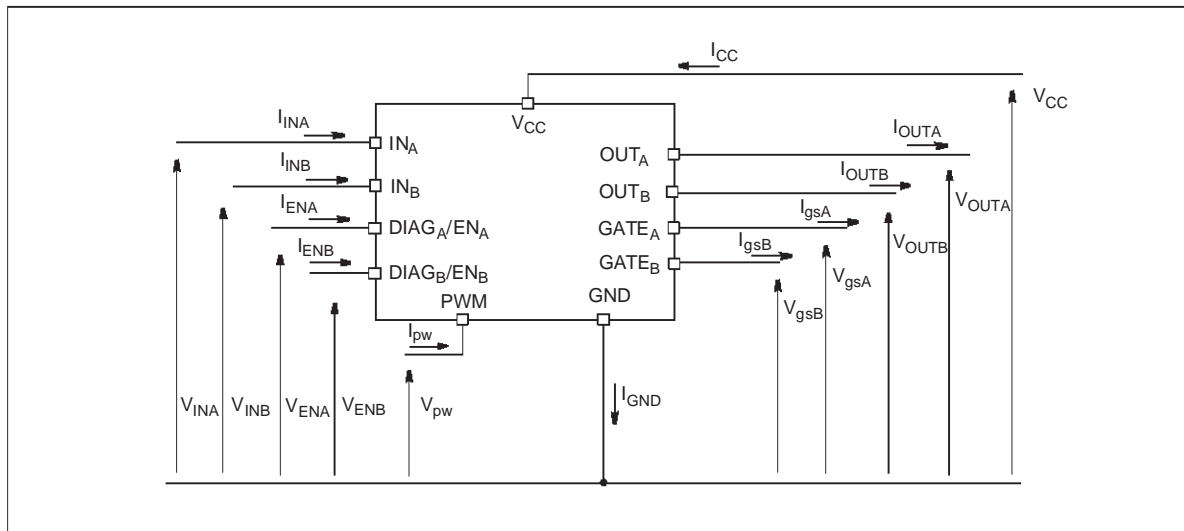


(*) See note at page 5

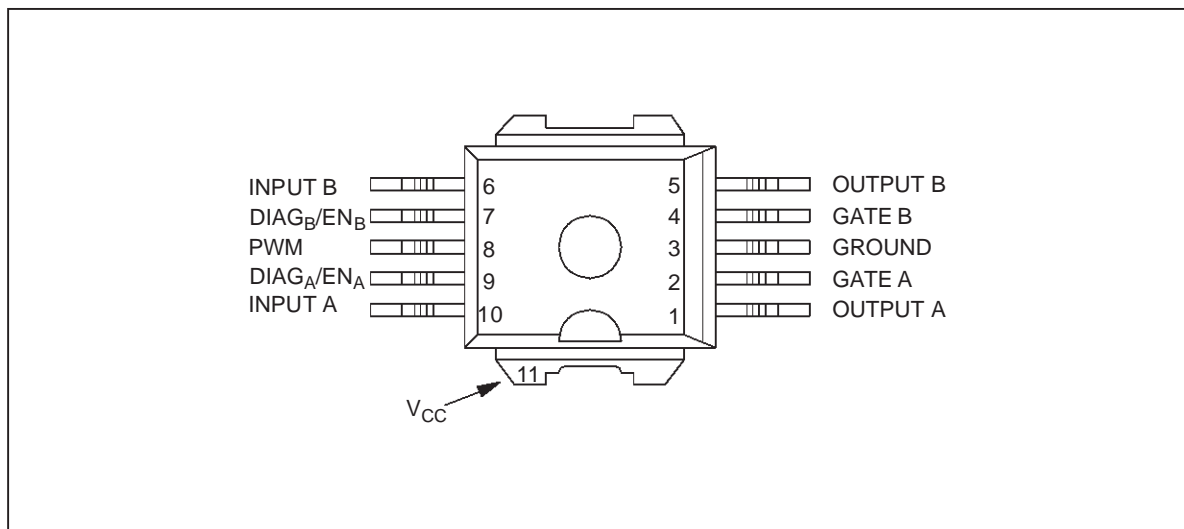
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	-0.3 .. 40	V
I_{max1}	Maximum output current (continuous)	15	A
I_{max2}	Maximum output current (250 ms pulse duration)	20	A
I_R	Reverse output current (continuous)	-15	A
I_{IN}	Input current	+/- 10	mA
I_{EN}	Enable pin current	+/- 10	mA
I_{pw}	PWM pin current	+/- 10	mA
I_{gs}	Output gate current	+/- 20	mA
V_{ESD}	Electrostatic discharge (R=1.5kΩ, C=100pF)	2000	V
T_j	Junction operating temperature	-40 to 150	°C
T_{STG}	Storage temperature	-55 to 150	°C

CURRENT AND VOLTAGE CONVENTIONS



CONNECTION DIAGRAM (TOP VIEW)



THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case (per channel) (MAX)	1.4	°C/W
$R_{thj-amb}^{(*)}$	Thermal resistance junction-ambient (MAX)	50	°C/W

(*) When mounted using the recommended pad size on FR-4 board (See AN515 Application Note).

ELECTRICAL CHARACTERISTICS ($V_{CC}=9V$ up to 18V; $-40^{\circ}C < T_j < 150^{\circ}C$; unless otherwise specified)

POWER

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{CC}	Operating supply voltage		5.5		26	V
R_{ON}	On state resistance	$I_{LOAD}=12A$ $I_{LOAD}=12A; T_j=25^{\circ}C$		26	50 30	mΩ mΩ
I_s	Supply current	ON state OFF state			15 40	mA μA
V_{gate}	Gate output voltage		5.0		8.5	V
$V_{gs,cl}$	Gate output clamp voltage	$I_{gs}=-1 mA$	6.8	7.4	8.5	V

SWITCHING ($V_{CC}=13V$, $R_{LOAD}=1.1\Omega$)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit	
$t_{D(on)}$	Turn-on delay time	Input rise time $< 1\mu s$ (see fig. 1)		50	150	μs	
$t_{D(off)}$	Turn-off delay time			45	135	μs	
t_r	Output voltage rise time				50	150	μs
t_f	Output voltage fall time				40	120	μs
$(dV_{OUT}/dt)_{on}$	Turn-on voltage slope				160	500	V/ms
$(dV_{OUT}/dt)_{off}$	Turn-off voltage slope				230	1200	V/ms
$t_{d(ong)}$	V_{gs} Turn-on delay time	$C1=4.7nF$ Break to ground configuration (see fig. 2)		0.5	2	μs	
t_{rg}	V_{gs} rise time			2.6	10	μs	
$t_{d(offg)}$	V_{gs} Turn-off delay time			1.0	5.0	μs	
t_{fg}	V_{gs} fall time			2.2	10	μs	
t_{del}	External MOSFET turn-on dead time	(see fig. 3)	150	600	1800	μs	

PROTECTION AND DIAGNOSTIC

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{USD}	Undervoltage shut-down				5.5	V
V_{OV}	Overvoltage shut-down		36	43		V
I_{LIM}	Current limitation		30	45		A
T_{TSD}	Thermal shut-down temperature	$V_{IN}=3.25 V$	150	170	200	°C
V_{ocl}	Output turn-off clamp voltage	$I_{LOAD}=12A, L=6mH$	$V_{CC}-55$		$V_{CC}-41$	V
V_{sat}	External MOSFET saturation voltage detection threshold		2.5	4.2	5.5	V

ELECTRICAL CHARACTERISTICS (continued)

PWM

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{pwl}	PWM low level voltage				1.5	V
I_{pwl}	PWM pin current	$V_{pw}=1.5V$	1			μA
V_{pwh}	PWM high level voltage		3.25			V
I_{pwh}	PWM pin current	$V_{pw}=3.25V$			10	μA
V_{pwhyst}	PWM hysteresis voltage		0.5			V
V_{pwcl}	PWM clamp voltage	$I_{pw} = 1 \text{ mA}$ $I_{pw} = -1 \text{ mA}$	$V_{CC}+0.3$ -5.0	$V_{CC}+0.7$ -3.5	$V_{CC}+1.0$ -2.0	V V
V_{pwtest}	Test mode PWM pin voltage		-3.5	-2.0	-0.5	V
I_{pwtest}	Test mode PWM pin current	$V_{pwtest} = -2.0 \text{ V}$	-2000	-500		μA

LOGIC INPUT (IN_A/IN_B)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{IL}	Input low level voltage				1.5	V
I_{INL}	Input current	$V_{IN}=1.5 \text{ V}$	1			μA
V_{IH}	Input high level voltage		3.25			V
I_{INH}	Input current	$V_{IN}=3.25 \text{ V}$			10	μA
V_{IHYST}	Input hysteresis voltage		0.5			V
V_{ICL}	Input clamp voltage	$I_{IN}=1\text{mA}$ $I_{IN}=-1\text{mA}$	6.8 -1.0	7.4 -0.7	8.5 -0.3	V V

ENABLE (LOGIC I/O PIN)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{ENL}	Enable low level voltage	Normal operation (DIAG _X /EN _X pin acts as an input pin)			1.5	V
I_{ENL}	Enable pin current	$V_{EN}=1.5 \text{ V}$	1			μA
V_{ENH}	Enable high level voltage	Normal operation (DIAG _X /EN _X pin acts as an input pin)	3.25			V
I_{ENH}	Enable pin current	$V_{EN}=3.25 \text{ V}$			10	μA
V_{EHYST}	Enable hysteresis voltage	Normal operation (DIAG _X /EN _X pin acts as an input pin)	0.5			V
V_{ENCL}	Enable clamp voltage	$I_{EN}=1\text{mA}$ $I_{EN}=-1\text{mA}$	6.8 -1.0	7.4 -0.7	8.5 -0.3	V V
V_{DIAG}	Enable output low level voltage	Fault operation (DIAG _X /EN _X pin acts as an input pin)			0.4	V
		$I_{EN}=1.6 \text{ mA}$				

WAVEFORMS AND TRUTH TABLE

TRUTH TABLE IN NORMAL OPERATING CONDITIONS

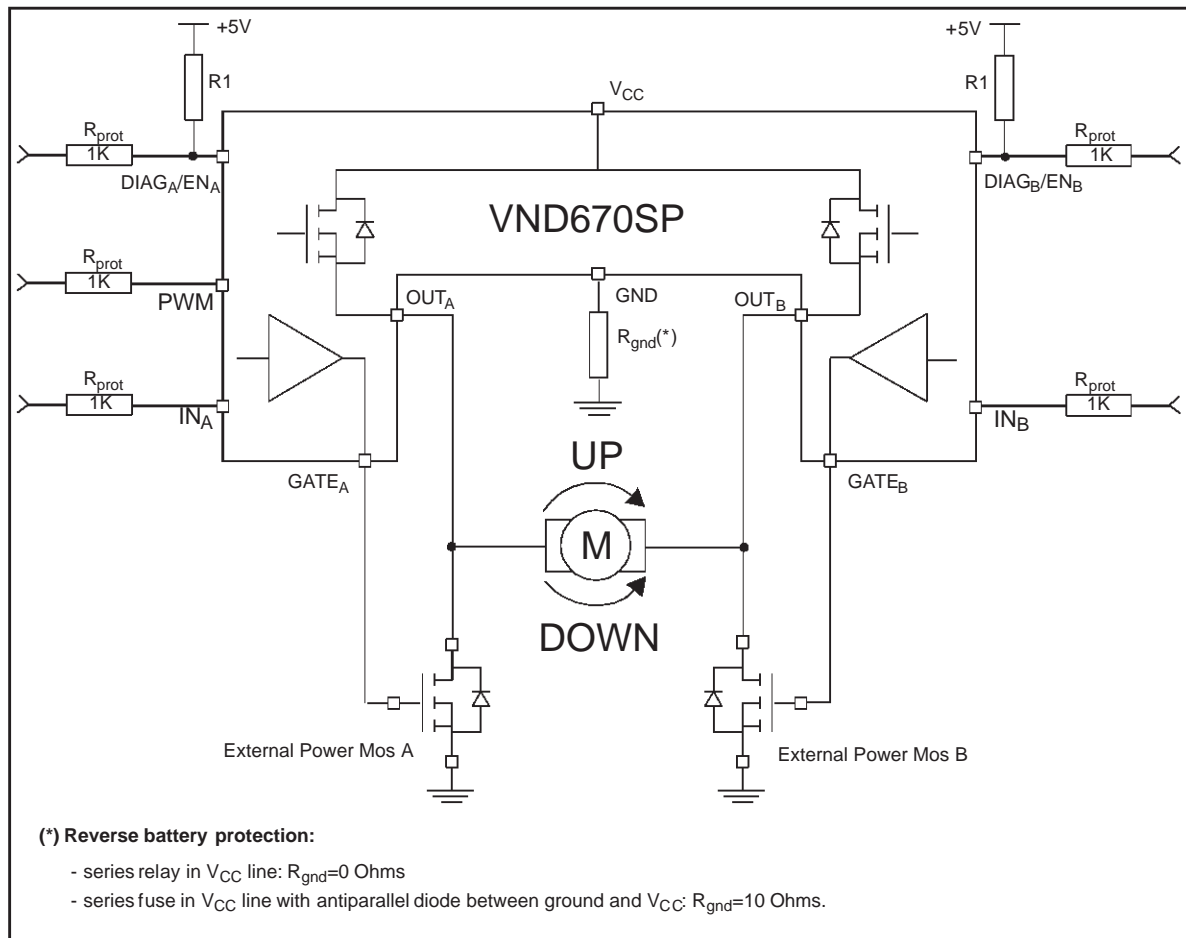
In normal operating conditions the DIAG_X/EN_X pin is considered as an input pin by the device. This pin must be externally pulled high.

IN _A	IN _B	DIAG _A /EN _A	DIAG _B /EN _B	OUT _A	OUT _B	GATE _A	GATE _B	Comment
1	1	1	1	H	H	L	L	Brake to V _{CC}
1	0	1	1	H	OPEN	L	H	Clockwise
0	1	1	1	OPEN	H	H	L	Counter cw
0	0	1	1	OPEN	OPEN	H	H	Brake to GND
X	X	0	0	OPEN	OPEN	L	L	Stand by
1	X	1	0	H	OPEN	L	L	HS _A only
0	X	1	0	OPEN	OPEN	H	L	MOS _A only
X	1	0	1	OPEN	H	L	L	HS _B only
X	0	0	1	OPEN	OPEN	L	H	MOS _B only

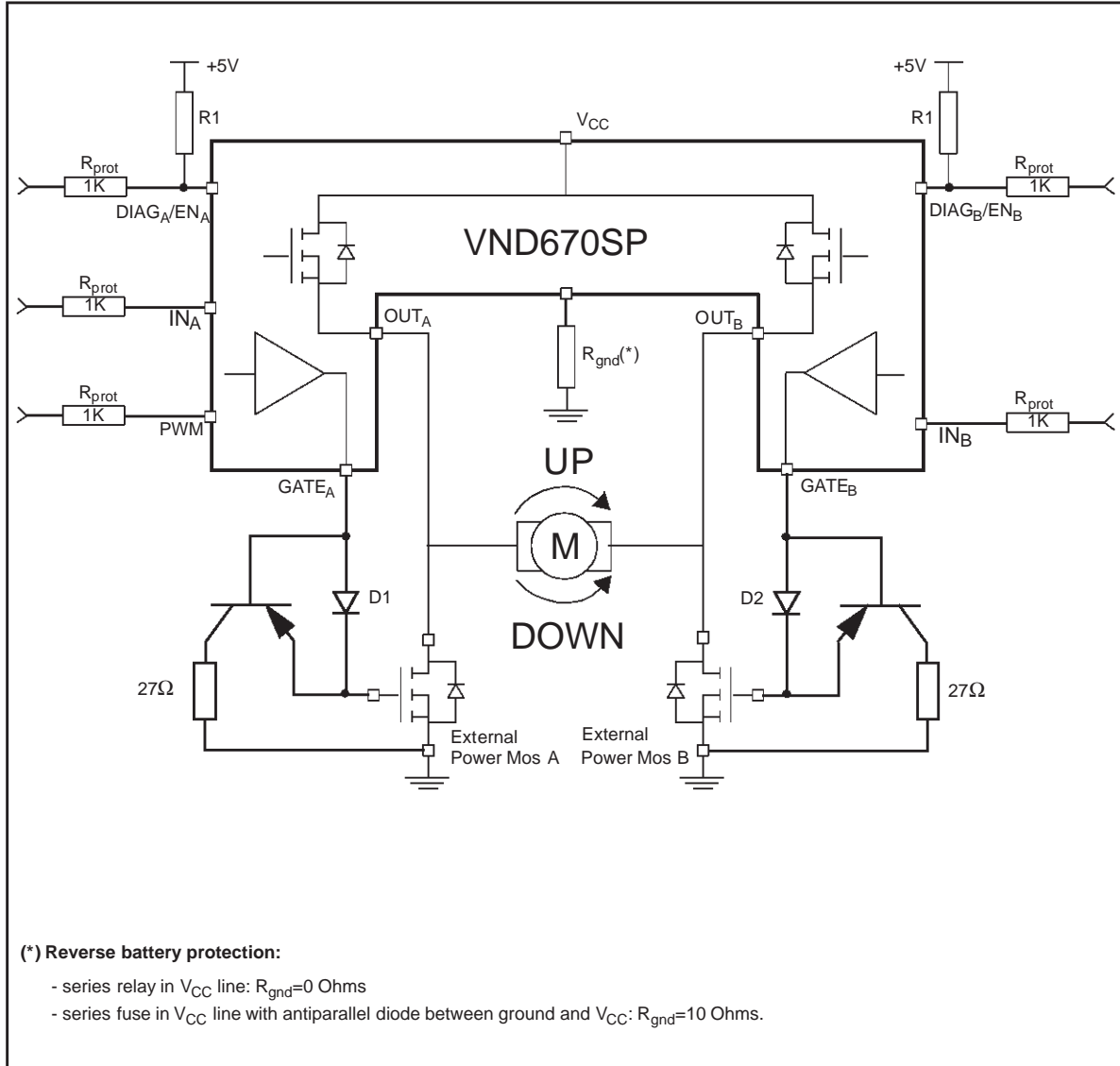
PWM pin usage:

In all cases, a "0" on the PWM pin will turn-off both GATE_A and GATE_B outputs. When PWM rises back to "1", GATE_A or GATE_B turn on again depending on the input pin state.

TYPICAL APPLICATION CIRCUIT FOR DC TO 10KHz PWM OPERATION



TYPICAL APPLICATION CIRCUIT FOR A 20KHZ PWM OPERATION



WAVEFORMS AND TRUTH TABLE (CONTINUED)

In case of a fault condition the DIAG_X/EN_X pin is considered as an output pin by the device.

The fault conditions are:

- overtemperature on one or both high sides;
- short to battery condition on the output (saturation detection on the external connected Power MOSFET).

Possible origins of fault conditions may be:

OUT_A is shorted to ground ---> overtemperature detection on high side A.

OUT_A is shorted to V_{CC} ---> external Power MOSFET saturation detection (driven by GATE_A).

When a fault condition is detected, the user can know which power element is in fault by monitoring the IN_A, IN_B, DIAG_A/EN_A and DIAG_B/EN_B pins.

In any case, when a fault is detected, the faulty half bridge is latched off. To turn-on the respective output (GATE_X or OUT_X) again, the input signal must rise from low to high level.

TRUTH TABLE IN FAULT CONDITIONS (detected on OUT_A)

IN _A	IN _B	DIAG _A /EN _A	DIAG _B /EN _B	OUT _A	OUT _B	GATE _A	GATE _B
1	1	0	1	OPEN	H	L	L
1	0	0	1	OPEN	OPEN	L	H
0	1	0	1	OPEN	H	L	L
0	0	0	1	OPEN	OPEN	L	H
X	X	0	0	OPEN	OPEN	L	L
1	X	0	0	OPEN	OPEN	L	L
0	X	0	0	OPEN	OPEN	L	L
X	1	0	1	OPEN	H	L	L
X	0	0	1	OPEN	OPEN	L	H



Fault Information



Protection Action

TEST MODE

The PWM pin allows to test the load connection between two half-bridges. In the test mode (V_{pwm}=-2V) the external Power Mos gate drivers are disabled. The IN_A or IN_B inputs allow to turn-on the High Side A or B, respectively, in order to connect one side of the load at V_{CC} voltage. The check of the voltage on the other side of the load allow to verify the continuity of the load connection. In case of load disconnection the DIAD_X/EN_X pin corresponding to the faulty output is pulled down.

ELECTRICAL TRANSIENT REQUIREMENTS

ISO T/R 7637/1 Test Pulse	Test Level I	Test Level II	Test Level III	Test Level IV	Test Levels Delays and Impedance
1	-25V	-50V	-75V	-100V	2ms, 10Ω
2	+25V	+50V	+75V	+100V	0.2ms, 10Ω
3a	-25V	-50V	-100V	-150V	0.1μs, 50Ω
3b	+25V	+50V	+75V	+100V	0.1μs, 50Ω
4	-4V	-5V	-6V	-7V	100ms, 0.01Ω
5	+26.5V	+46.5V	+66.5V	+86.5V	400ms, 2Ω

ISO T/R 7637/1 Test Pulse	Test Levels Result I	Test Levels Result II	Test Levels Result III	Test Levels Result IV
1	C	C	C	C
2	C	C	C	C
3a	C	C	C	C
3b	C	C	C	C
4	C	C	C	C
5	C	E	E	E

Class	Contents
C	All functions of the device are performed as designed after exposure to disturbance.
E	One or more functions of the device are not performed as designed after exposure to disturbance and cannot be returned to proper operation without replacing the device.

Figure 1: Test conditions for High Side switching times measurement.

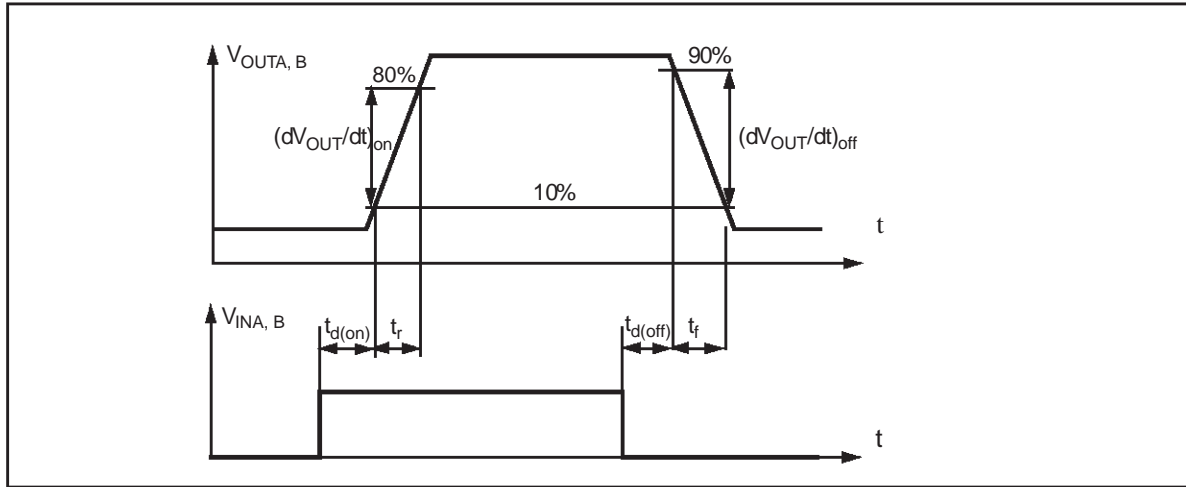


Figure 2: Test conditions for external Power MOSFET switching times measurement.

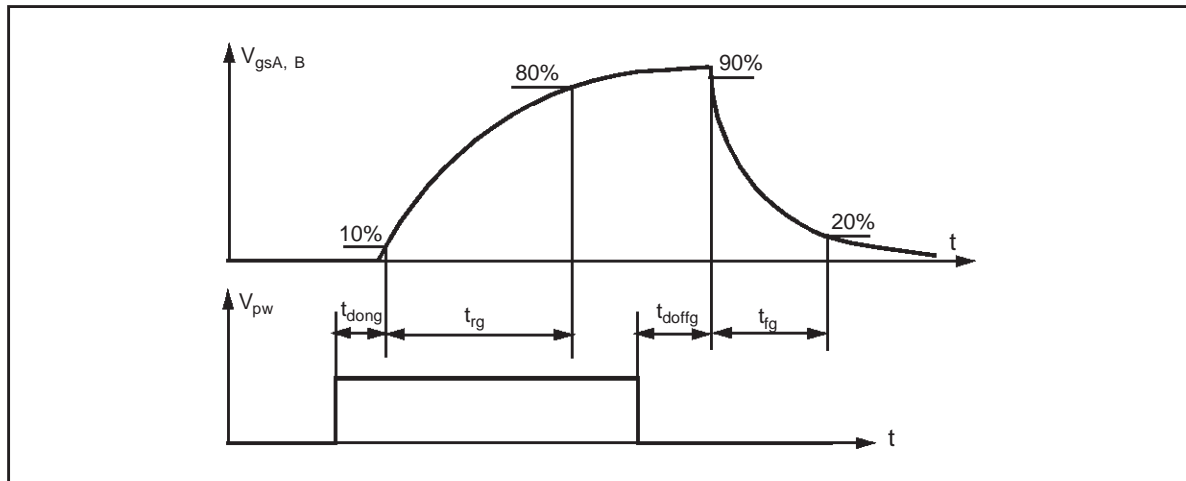
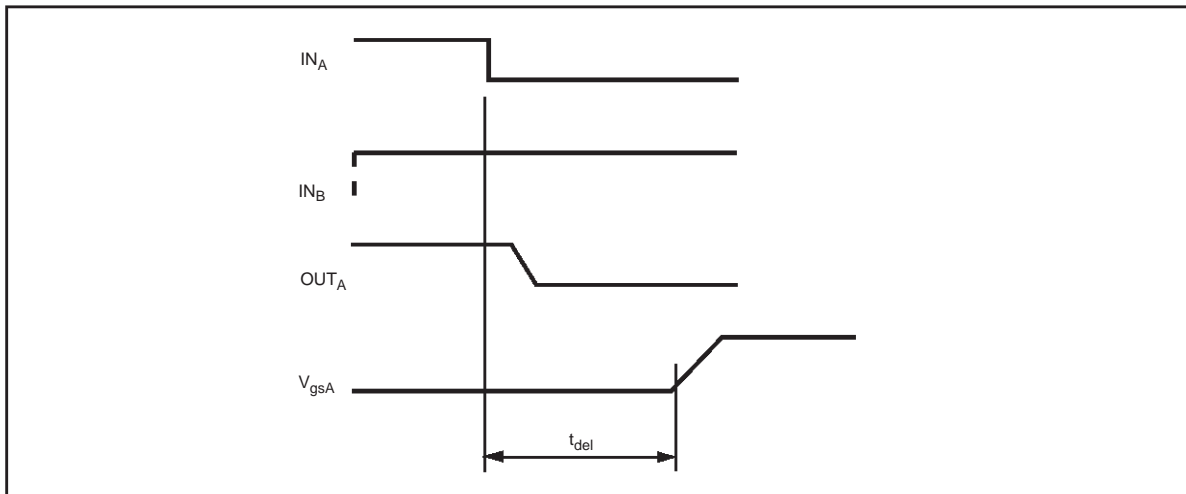
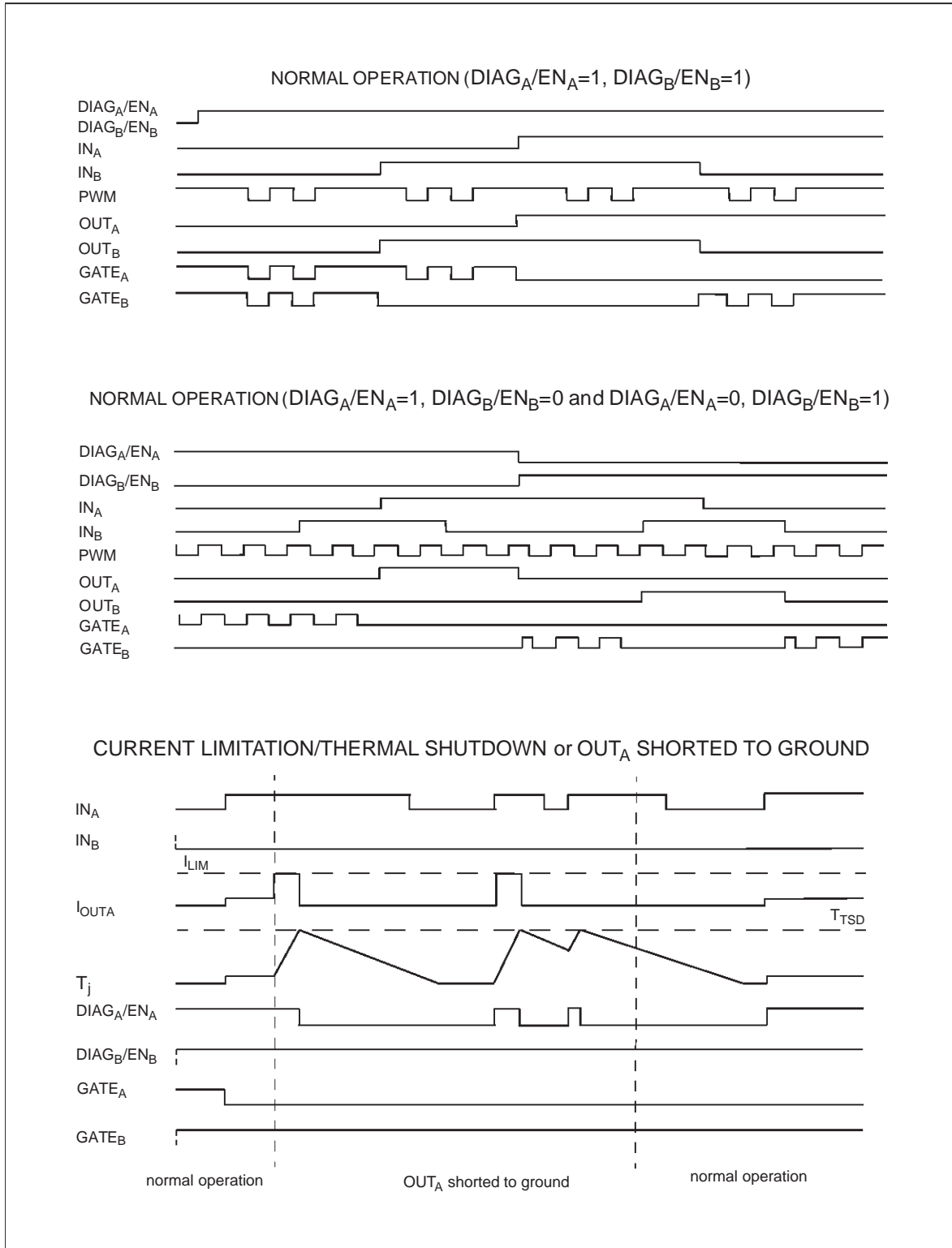


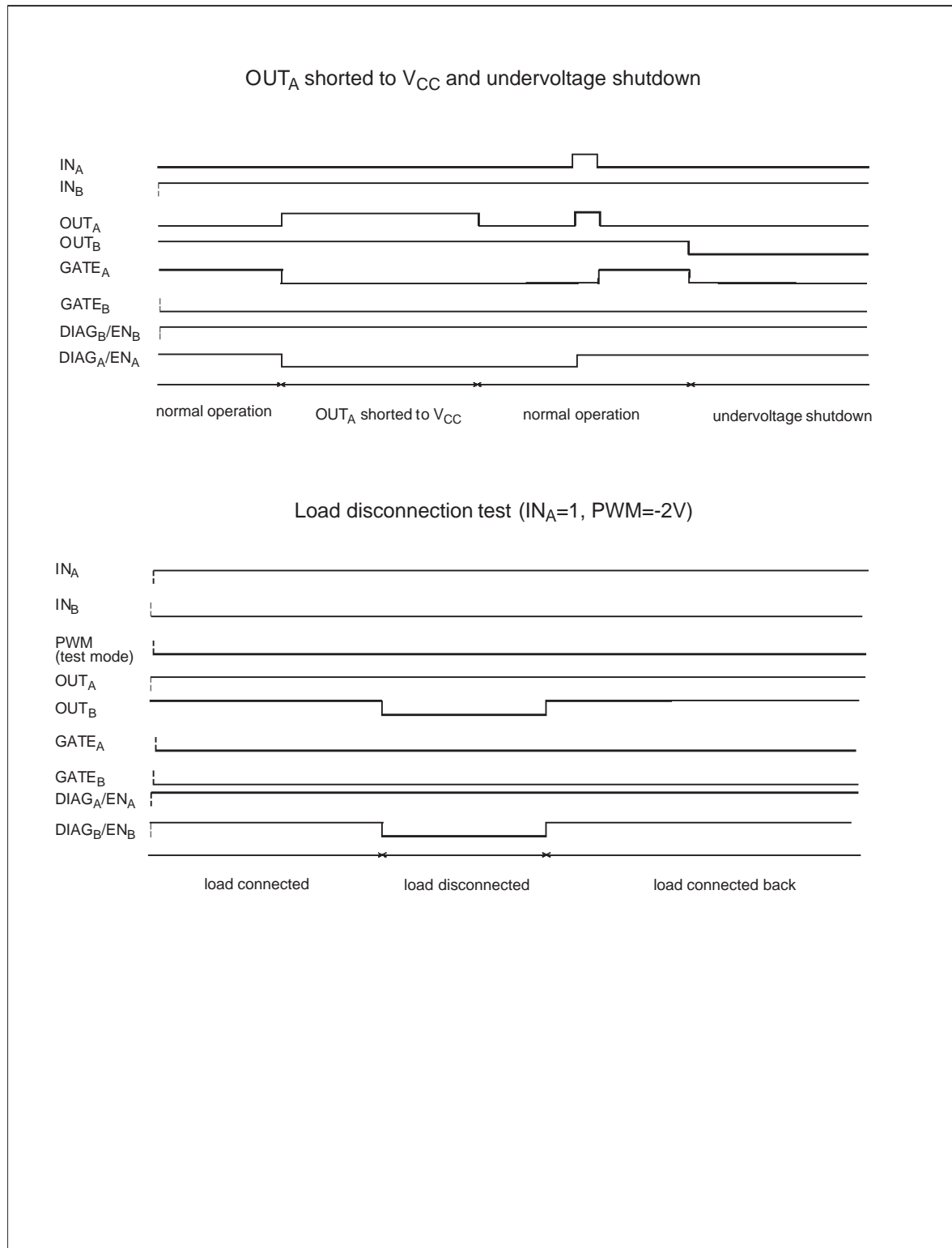
Figure 3: Definition of the external Power MOSFET turn-on dead time t_{del}



Waveforms

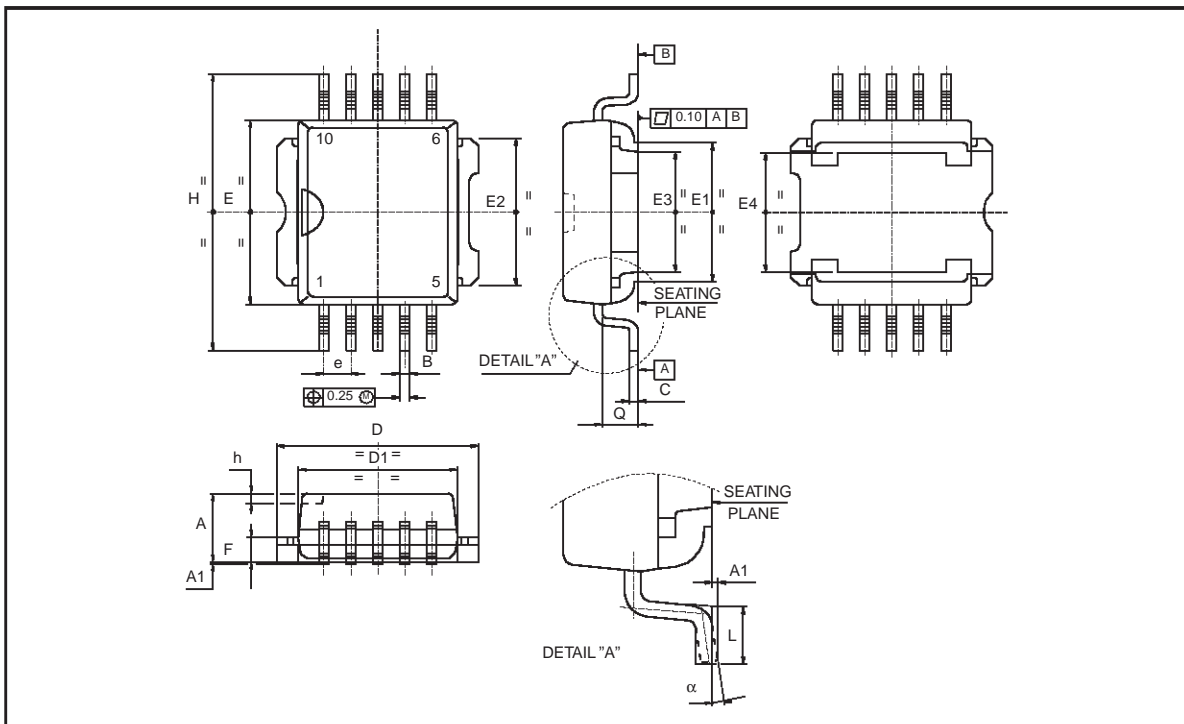


Waveforms (Continued)



PowerSO-10™ MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	3.35		3.65	0.132		0.144
A1	0.00		0.10	0.000		0.004
B	0.40		0.60	0.016		0.024
c	0.35		0.55	0.013		0.022
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.300
E	9.30		9.50	0.366		0.374
E1	7.20		7.40	0.283		0.291
E2	7.20		7.60	0.283		300
E3	6.10		6.35	0.240		0.250
E4	5.90		6.10	0.232		0.240
e		1.27			0.050	
F	1.25		1.35	0.049		0.053
H	13.80		14.40	0.543		0.567
h		0.50			0.002	
L	1.20		1.80	0.047		0.070
Q		1.70			0.067	
α	0°		8°			



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